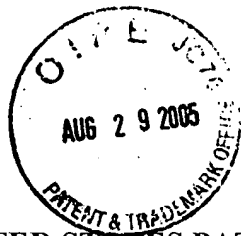


Docket No.: 067162-0021



PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

|                             |   |                           |
|-----------------------------|---|---------------------------|
| In re Application of        | : | Customer Number: 20277    |
|                             | : |                           |
| Ryu MAKABE, et al.          | : | Confirmation Number: 4281 |
|                             | : |                           |
| Application No.: 10/662,276 | : | Group Art Unit: 2813      |
|                             | : |                           |
| Filed: September 16, 2003   | : | Examiner: Tuan H. Nguyen  |
|                             | : |                           |

For: SEMICONDUCTOR WAFER, SEMICONDUCTOR CHIP AND DICING METHOD OF A SEMICONDUCTOR WAFER

**AMENDMENT**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

The following amendment and remarks are submitted in response to the non-final Office Action dated April 5, 2005.

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper. This listing of claims replaces all prior versions, and listings, of claims in the application.

Remarks begin on page 5 of this paper.